

DOCKET NO: 248983US2DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
MICHIAKI HIYOSHI : ATTN: APPLICATION DIVISION
SERIAL NO: NEW U.S. PCT APPLN. :
(Based on 09/917,876)
FILED: HEREWITH :
FOR: HERMETICALLY SEALED :
SEMICONDUCTOR POWER
MODULE AND LARGE SCALE
MODULE COMPRISING THE
SAME

PRELIMINARY AMENDMENT

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Prior to examination on the merits, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page of this paper.

Remarks/Arguments begin on page 11 of this paper.